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Dimensions

Chip Size	2225
L	5.6mm +/-0.4mm
W	6.4mm +/-0.4mm
T	1.4mm +/-0.15mm
B	0.6mm +/-0.35mm

Packaging Specifications

Packaging	Waffle, Tray
Packaging Quantity	20

General Information

Series	SMD Indust COG HVHT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Gold
Marking	No
AEC-Q200	No
Component Weight	300 mg
Miscellaneous	Moisture Sensitive Packaging. Gold (Au) 1.97 - 11.8 micro inches.
Shelf Life	26 Weeks
MSL	1

Specifications

Capacitance	330 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	2000 VDC
Dielectric Withstanding Voltage	2400 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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